

Amendments To The Claims:

Claims 1-9 (Canceled).

10. (Currently Amended) A method Method for producing an electronic module ~~in the shape of a ball housing combining~~ having a network of interconnection and/or shielding balls (7) or geometrically identical preforms and surface-mounted components (2) on the same side of a substrate (1), said substrate having a mounting surface having predetermined mounting lands for the interconnection and/or shielding balls (7) and surface-mounted components and said surface-mounted components being electronic devices used for ensuring electronic function, thus making the module directly connectable to a printed circuit (3), wherein the method including:

depositing soldering cream (8) is deposited simultaneously onto the mounting lands for the surface-mounted components and the interconnection and/or shielding balls, which are to be located on the same mounting surface of the substrate, simultaneously;

transferring the said surface-mounted components are transferred onto the deposited soldering cream on the corresponding mounting lands;

transferring the interconnection and/or shielding balls are transferred collectively onto the the deposited soldering cream on the corresponding mounting lands of on the mounting surface, which is the same side of the substrate as for the surface-mounted components intended for them by an appropriate device; and

soldering with a single reflow cycle permits simultaneous soldering of the surface-mounted components and the interconnection and/or shielding balls onto the substrate, simultaneously,

such that the electronic module is in the shape of a ball housing and is directly connectable to the printed circuit.

11. (Currently Amended) The method Method as claimed in claim 10, wherein the soldering cream (8) is deposited via serigraphy.

12. (Currently Amended) The method Method as claimed in claim 10, wherein the soldering cream (8) is deposited by syringe.

13. (Currently Amended) The method Method as claimed in claim 10, further comprising the step of connecting the electronic module to the printed circuit, the printed circuit having a ground plane, wherein it makes it possible to produce the electronic module and printed circuit

combination is capable of producing an electromagnetic shield integrated directly into the electronic module by conducting connections (19)(21) to the ground plane (20) of the printed circuit (3).

14. (Currently Amended) The method Method as claimed in claim 10, wherein decoupling capacitors (17) and/or serial resistors (16) and/or filtering cells and/or quartz adapter condensers are/is integrated ~~it makes it possible to integrate~~ as close to the interconnection and/or shielding connecting balls (7) as possible and on the mounting surface ~~same side~~ of the electronic module ~~decoupling capacitors (17) and/or serial resistors (16) and/or filtering cells and/or quartz adapter condensers~~.

15. (Currently Amended) The method Method as claimed in claims 10, the electronic module having a gripping surface, wherein the gripping of the ~~wherein the side of the module opposite the side comprising the balls and the components allows gripping of the~~ electronic module may be gripped by suction and transferred to the printed circuit.

Claims 16-18 (Canceled).

19. (Currently Amended) The method Method as claimed in claim 10, the electronic module being directly connectable by soldering to the printed circuit.

20. (Currently Amended) The method Method as claimed in claim 10, wherein the interconnection and/or shielding balls have a diameter greater than the height of said surface-mounted components.